

2018 7th Electronic System-Integration Technology Conference (ESTC 2018)

**Dresden, Germany
18 – 21 September 2018**



**IEEE Catalog Number: CFP18TEM-POD
ISBN: 978-1-5386-6815-3**

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IEEE Catalog Number:	CFP18TEM-POD
ISBN (Print-On-Demand):	978-1-5386-6815-3
ISBN (Online):	978-1-5386-6814-6

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